

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/23/13886	
1.3 Title of PCN	ST Shenzhen (China) TSSOP20 package copper alloy bonding wire introduction on STM32C01x, STM32C03x, STM32G05x and STM32G06x listed products	
1.4 Product Category	STM32C01x STM32C03x STM32G05x STM32G06x	
1.5 Issue date	2023-01-22	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Shenzhen (China)

4. Description of change

	Old	New
4.1 Description	Wire bonding material: - Amkor ATP (Philippines) gold wire	Wire bonding material: - ST Shenzhen (China) copper alloy wire - Amkor ATP (Philippines) gold wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve Capacity and flexibility to support customer growing demand.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2023-03-28
7.2 Intended start of delivery	2023-04-06
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13886 MDG-GPM-RER2219 PCN13703 PCN13886 STS TSSOP20 Cu alloy wire intro on STM32C0x-G0x - reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-01-22

9. Attachments (additional documentations)		
13886 Public product.pdf 13886 MDG-GPM-RER2219 PCN13703 PCN13886 STS TSSOP20 Cu alloy wire intro on STM32C0x-G0x - reliability plan.pdf 13886 PCN13886_Additional information.pdf		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32C011F6P6	

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